

Notice of References Cited

Application/Control No.

09/752,505

Applicant(s)/Patent Under
Reexamination
STEWART, THOMAS

Examiner

Samuel Broda

Art Unit

2123

Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,397,153 B1	05-2002	Yamagishi et al.	702/42
	B	US-6,341,258 B1	01-2002	Inoue et al.	702/56
	C	US-5,602,759 A	02-1997	Harashima et al.	702/56
	D	US-5,602,757 A	02-1997	Haseley et al.	702/56
	E	US-5,388,056 A	02-1995	Horiuchi et al.	702/56
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Wong et al, "Durability/Reliability of BGA Solder Joints Under Vibration Environment", IEEE Proceedings of the 50th Electronic Components and Technology Conference, pp. 1083-1088 (May 2000)
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.